

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# **TJ60S06M3L**

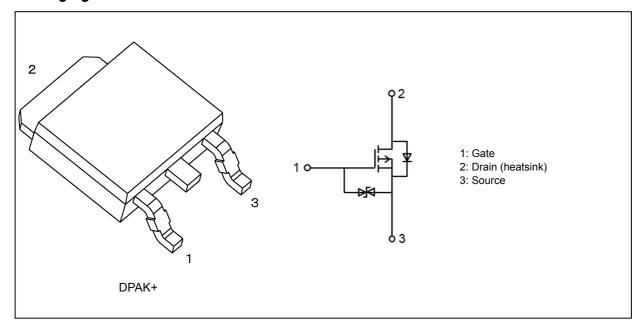
## 1. Applications

- · Automotive
- · Motor Drivers
- · DC-DC Converters
- Switching Voltage Regulators

#### 2. Features

- (1) AEC-Q101 qualified
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 8.6 \text{ m}\Omega$  (typ.) ( $V_{GS} = -10 \text{ V}$ )
- (3) Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max)} \text{ (V}_{DS} = -60 \text{ V)}$
- (4) Enhancement mode:  $V_{th}$  = -2.0 to -3.0 V ( $V_{DS}$  = -10 V,  $I_D$  = -1 mA)

## 3. Packaging and Internal Circuit



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## 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

| Characteristics                       | Symbol   | Rating           | Unit       |    |
|---------------------------------------|----------|------------------|------------|----|
| Drain-source voltage                  |          | $V_{DSS}$        | -60        | V  |
| Gate-source voltage                   |          | $V_{GSS}$        | -20/+10    |    |
| Drain current (DC)                    | (Note 1) | I <sub>D</sub>   | -60        | Α  |
| Drain current (pulsed)                | (Note 1) | I <sub>DP</sub>  | -120       |    |
| Power dissipation (T <sub>c</sub> = 2 | 25°C)    | P <sub>D</sub>   | 100        | W  |
| Single-pulse avalanche energy         | (Note 2) | E <sub>AS</sub>  | 132        | mJ |
| Avalanche current                     |          | I <sub>AR</sub>  | -60        | Α  |
| Channel temperature                   | (Note 3) | T <sub>ch</sub>  | 175        | ç  |
| Storage temperature                   | (Note 3) | T <sub>stg</sub> | -55 to 175 |    |

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics                    |                       | Max | Unit |
|------------------------------------|-----------------------|-----|------|
| Channel-to-case thermal resistance | R <sub>th(ch-c)</sub> | 1.5 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2:  $V_{DD}$  = -25 V,  $T_{ch}$  = 25°C (initial), L = 50  $\mu$ H,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -60 A

Note 3: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

# 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                         | Symbol               | Test Condition                                     | Min  | Тур. | Max  | Unit |
|---|----------------------|--|------|------|------|------|
| Gate leakage current                    | I <sub>GSS</sub>     | V <sub>GS</sub> = -16/+10 V, V <sub>DS</sub> = 0 V | _    | _    | ±10  | μА   |
| Drain cut-off current                   | I <sub>DSS</sub>     | V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V     | _    | _    | -10  |      |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub> | $I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$       | -60  | _    | _    | ٧    |
| Drain-source breakdown voltage (Note 4) | V <sub>(BR)DSX</sub> | I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 10 V    | -50  | _    | _    |      |
| Gate threshold voltage                  | $V_{th}$             | $V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$    | -2.0 | _    | -3.0 |      |
| Drain-source on-resistance              | R <sub>DS(ON)</sub>  | $V_{GS} = -6 \text{ V}, I_D = -30 \text{ A}$       | _    | 9.8  | 14.5 | mΩ   |
|   |                      | $V_{GS}$ = -10 V, $I_D$ = -30 A                    | _    | 8.6  | 11.2 |      |

Note 4: If a forward bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

# 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                | Symbol           | Test Condition  | Min | Тур. | Max | Unit |
|--------------------------------|------------------|---|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub> | V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz | _   | 7760 | _   | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub> |   | _   | 530  | _   |      |
| Output capacitance             | C <sub>oss</sub> |   | _   | 690  | _   |      |
| Switching time (rise time)     | t <sub>r</sub>   | See Figure 6.2.1.   | _   | 100  | _   | ns   |
| Switching time (turn-on time)  | t <sub>on</sub>  |   | _   | 127  | _   |      |
| Switching time (fall time)     | t <sub>f</sub>   |   | _   | 250  | _   |      |
| Switching time (turn-off time) | t <sub>off</sub> |   | _   | 970  |     |      |

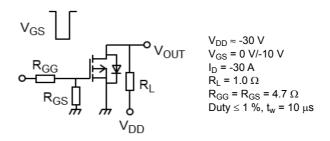


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                                 | Symbol          | Test Condition  | Min | Тур. | Max | Unit |
|---|-----------------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg              | $V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -60 \text{ A}$ | _   | 156  | _   | nC   |
| Gate-source charge                              | Q <sub>gs</sub> |   | 1   | 107  | _   |      |
| Gate-drain charge                               | $Q_{gd}$        |   | _   | 49   | _   |      |

# 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

| Characteristics                |          | Symbol           | Test Condition                                 | Min | Тур. | Max  | Unit |
|--------------------------------|----------|------------------|--|-----|------|------|------|
| Reverse drain current (DC)     | (Note 5) | I <sub>DR</sub>  | _  | _   | _    | -60  | Α    |
| Reverse drain current (pulsed) | (Note 5) | I <sub>DRP</sub> | _  | _   | _    | -120 |      |
| Diode forward voltage          |          | V <sub>DSF</sub> | I <sub>DR</sub> = -60 A, V <sub>GS</sub> = 0 V | _   | _    | 1.2  | V    |
| Reverse recovery time          |          | t <sub>rr</sub>  | I <sub>DR</sub> = -60 A, V <sub>GS</sub> = 0 V | _   | 51   | _    | ns   |
| Reverse recovery charge        |          | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 50 A/μs                 | _   | 39   | _    | nC   |

Note 5: Ensure that the channel temperature does not exceed 175°C.



## 7. Marking (Note)

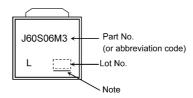


Fig. 7.1 Marking

Note: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS

compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the

restriction of the use of certain hazardous substances in electrical and electronic equipment.



#### 8. Characteristics Curves (Note)

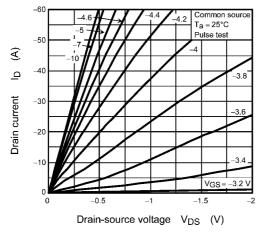
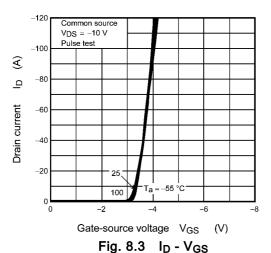
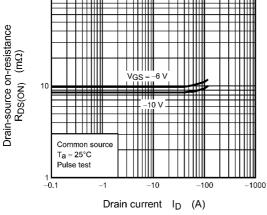


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>





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Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

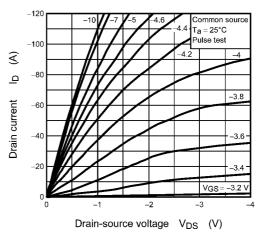


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

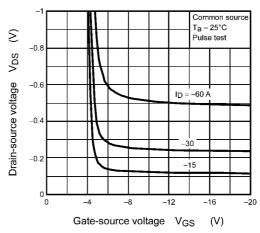


Fig. 8.4 V<sub>DS</sub> - V<sub>GS</sub>

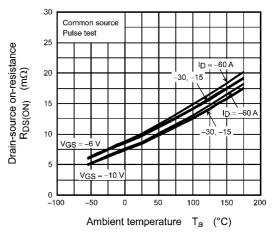


Fig. 8.6 R<sub>DS(ON)</sub> - T<sub>a</sub>



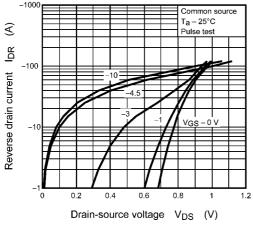


Fig. 8.7 IDR - VDS

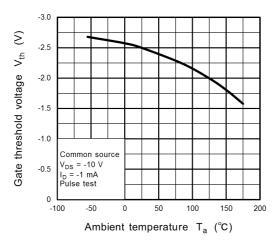


Fig. 8.9 V<sub>th</sub> - T<sub>a</sub>

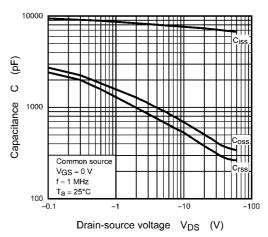


Fig. 8.8 Capacitance - V<sub>DS</sub>

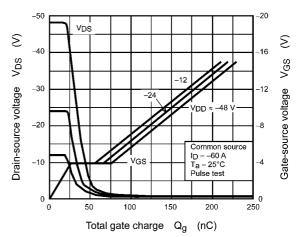


Fig. 8.10 Dynamic Input/Output Characteristics



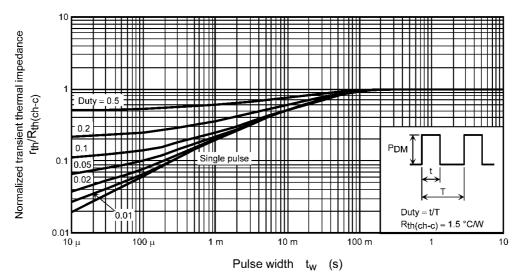


Fig. 8.11  $r_{th}/R_{th(ch-c)} - t_w$  (Guaranteed Maximum)

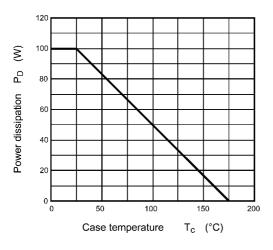


Fig. 8.12 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

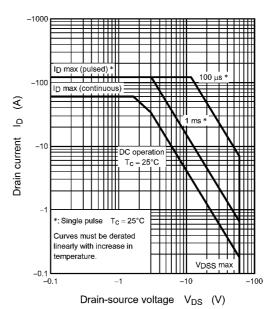


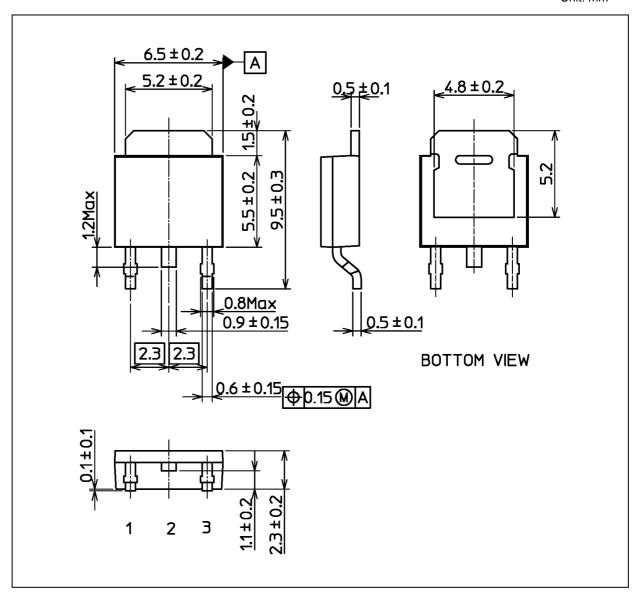
Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



# **Package Dimensions**

Unit: mm



Weight: 0.36 g (typ.)

|                 | Package Name(s) |
|-----------------|-----------------|
| TOSHIBA: 2-7M1A |                 |
| Nickname: DPAK+ |                 |



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